RICOH

R1524x-Y Series

200 mA 36 V Input Ultra Low Supply Current VR for Industrial Applications

No. EA-354-180524

OUTLINE

The R1524x is a CMOS-based ultra low supply current voltage regulator featuring 200 mA output current and 36 V input voltage. This device consists of an Output Short-circuit Protection Circuit, an Over-current Protection Circuit, and a Thermal Shutdown Circuit in addition to the basic regulator circuits. The operating temperature range is between −50°C to 125°C, and the maximum input voltage is 36 V. All these features allow this device to become an ideal power source for equipments used under high-temperature conditions.
The output voltages are internally fixed at either of the following: 1.8 V, 2.5 V, 2.8 V, 3.0 V, 3.3 V, 3.4 V, 5.0 V, 5.5 V, 6.0 V, 6.4 V, 8.0 V, 8.5 V and 9.0 V. The output voltage accuracy is ±0.6%.
The packages for this device range from high-density mounting to ultra high wattage. The R1524x is offered in five packages; a 5-pin SOT-23-5, a 5-pin SOT-89-5, a 6-pin HSOP-6J, a 6-pin DFN(PLP)1820-6, and an 8-pin HSOP-8E package.
This is a high-reliability semiconductor device for industrial applications (-Y) that has passed both the screening at high temperature and the reliability test with extended hours. This line of products operate in a wide temperature range from low temperature to high temperature to support harsh environment applications.

FEATURES

- Input Voltage Range (Maximum Rating) ············ 3.5 V to 36 V (50 V)
- Operating Temperature Range ························ –50°C to 125°C
- Supply Current·· Typ. 2.2 µA
- Standby Current··· Typ. 0.1 µA
- Dropout Voltage ··· Typ. 0.6 V (I_{OUT} = 200 mA, V_{OUT} = 5.0 V)
- Output Voltage Range ································· 1.8 V / 2.5 V / 2.8 V / 3.0 V / 3.3 V / 3.4V / 5.0 V / 5.5 V / 6.0 V / 6.4 V / 8.0 V / 8.5 V / 9.0 V
  *Contact Ricoh sales representatives for other voltages.
- Output Voltage Accuracy······························ ±0.6% (Ta = 25°C)
- Output Voltage Temperature-Drift Coefficient······· Typ. ±60 ppm/°C
- Line Regulation·· Typ. 0.01%/V (V_{SET} + 1 V ≤ V_{IN} ≤ 36 V)
- Built-in Output Short-circuit Protection Circuit ······ Typ. 80 mA
- Built-in Over-current Protection Circuit ··············· Typ. 350 mA
- Built-in Thermal Shutdown Circuit ····················· Thermal Shutdown Temperature: Typ. 160°C
- Ceramic capacitors are recommended to be used with this device ···························· C_{OUT} = 0.1 µF or more
- Packages ··· SOT-23-5, SOT-89-5, HSOP-6J, DFN(PLP)1820-6, HSOP-8E

APPLICATIONS

- Industrial equipments such as FAs and smart meters
- Equipments used under high-temperature conditions such as surveillance camera and vending machine
- Equipments accompanied by self-heating such as motor and lighting

SELECTION GUIDE

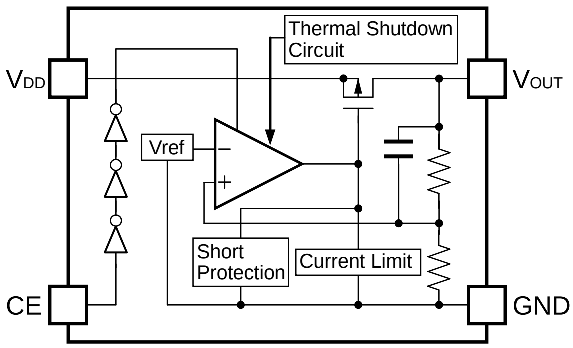
The set output voltage and the package type are user-selectable.

Selection Guide

Product Name	Package	Quantity per Reel	Pb Free	Halogen Free
R1524NxxxB-TR-YE	SOT-23-5	3,000 pcs	Yes	Yes
R1524HxxxB-T1-YE	SOT-89-5	1,000 pcs	Yes	Yes
R1524SxxxB-E2-YE	HSOP-6J	1,000 pcs	Yes	Yes
R1524KxxxB-TR-Y	DFN(PLP)1820-6	5,000 pcs	Yes	Yes
R1524SxxxH-E2-YE	HSOP-8E	1,000 pcs	Yes	Yes

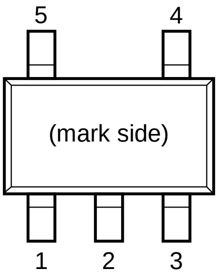
xxx: Specify the set output voltage (V_{SET})
1.8 V (018) / 2.5 V (025) / 2.8 V (028) / 3.0 V (030) / 3.3 V (033) / 3.4 V (034) /
5.0 V (050) / 5.5 V (055) / 6.0 V (060) / 6.4 V (064) / 8.0 V (080) / 8.5 V (085) / 9.0 V (090)
*Contact Ricoh sales representatives for other voltages.

BLOCK DIAGRAM

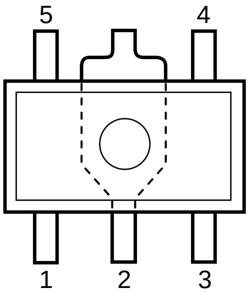


R1524x Block Diagram

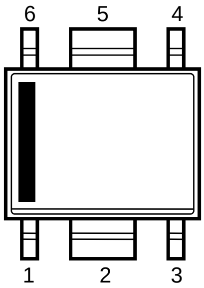
PIN DESCRIPTIONS



SOT-23-5 Pin Configuration

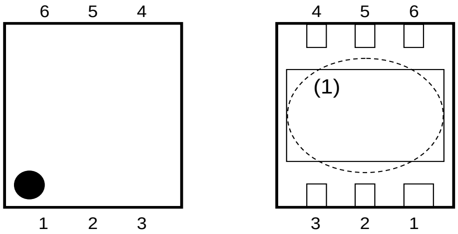


SOT-89-5 Pin Configuration



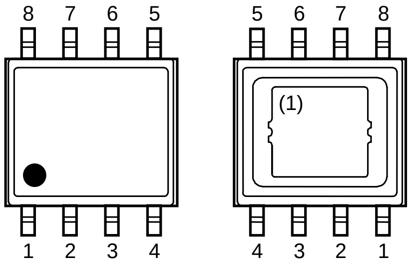
HSOP-6J Pin Configuration

Top View **Bottom View**



DFN(PLP)1820-6 Pin Configuration

Top View **Bottom View**



HSOP-8E Pin Configuration

SOT-23-5 Pin Descriptions

Pin No.	Symbol	Description
1	GND[2]	Ground Pin
2	GND[2]	Ground Pin
3	CE	Chip Enable Pin (Active-high)
4	V_{OUT}	Output Pin
5	V_{DD}	Input Pin

SOT-89-5 Pin Descriptions

Pin No.	Symbol	Description
1	V_{OUT}	Output Pin
2	GND[3]	Ground Pin
3	CE	Chip Enable Pin (Active-high)
4	GND[3]	Ground Pin
5	V_{DD}	Input Pin

[1] The tab on the bottom of the package enhances thermal performance and is electrically connected to GND (substrate level). It is recommended that the tab be connected to the ground plane on the board, or otherwise be left open.
[2] The GND pin must be wired together when it is mounted on board.
[3] The GND pin must be wired together when it is mounted on board.

HSOP-6J Pin Descriptions

Pin No.	Symbol	Description
1	V_{OUT}	Output Pin
2	GND(1)	Ground Pin
3	CE	Chip Enable Pin (Active-high)
4	GND(1)	Ground Pin
5	GND(1)	Ground Pin
6	V_{DD}	Input Pin

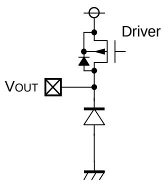
DFN(PLP)1820-6 Pin Descriptions

Pin No.	Symbol	Description
1	CE	Chip Enable Pin (Active-high)
2	NC	No Connection
3	GND	Ground Pin
4	V_{DD}	Input Pin
5	NC	No Connection
6	V_{OUT}	Output Pin

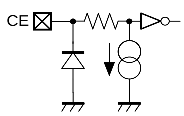
HSOP-8E Pin Descriptions

Pin No.	Symbol	Description
1	V_{OUT}	Output Pin
2	NC	No Connection
3	NC	No Connection
4	CE	Chip Enable Pin (Active-high)
5	GND	Ground Pin
6	NC	No Connection
7	NC	No Connection
8	V_{DD}	Input Pin

PIN EQUIVALENT CIRCUIT DIAGRAMS



V_{OUT} Pin



CE Pin

(1) The GND pin must be wired together when it is mounted on board.

ABSOLUTE MAXIMUM RATINGS

Absolute Maximum Ratings

Symbol	Item		Rating	Unit
V_{IN}	Input Voltage		−0.3 to 50	V
V_{IN}	Peak Input Voltage[1]		60	V
V_{CE}	Input Voltage (CE Pin)		−0.3 to 50	V
V_{OUT}	Output Voltage		−0.3 to V_{IN} + 0.3 ≤ 50	V
I_{OUT}	Output Current		300	mA
P_D	Power Dissipation[2] (JEDEC STD.51-7 Test Land Pattern)	SOT-23-5	830	mW
		SOT-89-5	3200	
		HSOP-6J	3400	
		DFN(PLP)1820-6	2700	
		HSOP-8E	3600	
Tj	Junction Temperature		−50 to 150	°C
Tstg	Storage Temperature Range		−55 to 150	°C

ABSOLUTE MAXIMUM RATINGS
Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause the permanent damages and may degrade the lifetime and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings are not assured.

RECOMMENDED OPERATING CONDITIONS

Recommended Operating Conditions

Symbol	Item	Rating	Unit
V_{IN}	Input Voltage	3.5 to 36	V
Ta	Operating Temperature Range	−50 to 125	°C

RECOMMENDED OPERATING CONDITIONS
All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if when they are used over such conditions by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

(1) Duration time: 200 ms
(2) Refer to *POWER DISSIPATION* for detailed information.

ELECTRICAL CHARACTERISTICS

C_{IN} = C_{OUT} = 0.1 μF, unless otherwise noted.

The specifications surrounded by ☐ are guaranteed by design engineering at -50°C ≤ Ta ≤ 125°C.

R1524x (-Y/-YE) (Ta = 25°C)

Symbol	Item	Conditions		Min.	Typ.	Max.	Unit
I_{SS}	Supply Current	V_{IN} = 14 V I_{OUT} = 0 mA	V_{SET} ≤ 5.0 V		2.2	6.5	μA
			5.0 V < V_{SET}		2.5	6.8	
Istandby	Standby Current	V_{IN} = 36 V, V_{CE} = 0 V			0.1	1.0	μA
V_{OUT}	Output Voltage	V_{SET} + 1 V ≤ V_{IN} ≤ 36 V I_{OUT} = 1 mA	Ta = 25°C	×0.994		×1.006	V
			−50°C ≤ Ta ≤ 125°C	×0.984		×1.016	
$\Delta V_{OUT}/\Delta I_{OUT}$	Load Regulation	V_{IN} = V_{SET} + 3.0 V 1 mA ≤ I_{OUT} ≤ 200 mA		Refer to the *Product-specific Electrical Characteristics*			
$\Delta V_{OUT}/\Delta V_{IN}$	Line Regulation	V_{SET} + 1 V ≤ V_{IN} ≤ 36 V, I_{OUT} = 1 mA	V_{SET} < 3.3 V	-20	5	20	mV
			3.3 V ≤ V_{SET}	-0.02	0.01	0.02	%/V
V_{DIF}	Dropout Voltage	I_{OUT} = 200 mA		Refer to the *Product-specific Electrical Characteristics*			
I_{LIM}	Output Current Limit	V_{IN} = V_{SET} + 3.0 V		220	350	420	mA
I_{SC}	Short Current Limit	V_{OUT} = 0 V		60	80	110	mA
V_{CEH}	CE Input Voltage "H"			2.0		36	V
V_{CEL}	CE Input Voltage "L"			0		1.0	V
I_{PD}	CE Pull-down Current				0.2	0.6	μA
T_{TSD}	Thermal Shutdown Temparature	Junction Temperature			160		°C
T_{TSR}	Thermal Shutdown Released Temperature	Junction Temperature			135		°C

All test items listed under Electrical Characteristics are done under the pulse load condition (Tj ≈ Ta = 25°C).

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The specifications surrounded by ☐ are guaranteed by design engineering at -50°C ≤ Ta ≤ 125°C.

R1524x (-Y/-YE) Product-specific Electrical Characteristics (Ta = 25°C)

Product Name	V_{OUT} (V) (Ta = 25°C)			V_{OUT} (V) (−50°C ≤ Ta ≤ 125°C)			$\Delta V_{OUT}/\Delta I_{OUT}$ (mV)			V_{DIF} (V)	
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	TYP.	MAX.
R1524x018x	1.7892	1.80	1.8108	1.7712	1.80	1.8288	-10	10	40	1.6	2.5
R1524x025x	2.4850	2.50	2.5150	2.4600	2.50	2.5400				1.2	2.2
R1524x028x	2.7832	2.80	2.8168	2.7552	2.80	2.8448					
R1524x030x	2.9820	3.00	3.0180	2.9520	3.00	3.0480					
R1524x033x	3.2802	3.30	3.3198	3.2472	3.30	3.3528				0.8	2.0
R1524x034x	3.3796	3.40	3.4204	3.3456	3.40	3.4544					
R1524x050x	4.9700	5.00	5.0300	4.9200	5.00	5.0800				0.6	1.2
R1524x055x	5.4670	5.50	5.5330	5.4120	5.50	5.5880	-18	18	72		
R1524x060x	5.9640	6.00	6.0360	5.9040	6.00	6.0960					
R1524x064x	6.3616	6.40	6.4384	6.2976	6.40	6.5024					
R1524x080x	7.9520	8.00	8.0480	7.8720	8.00	8.1280				0.5	1.3
R1524x085x	8.4490	8.50	8.5510	8.3640	8.50	8.6360					
R1524x090x	8.9460	9.00	9.0540	8.8560	9.00	9.1440					

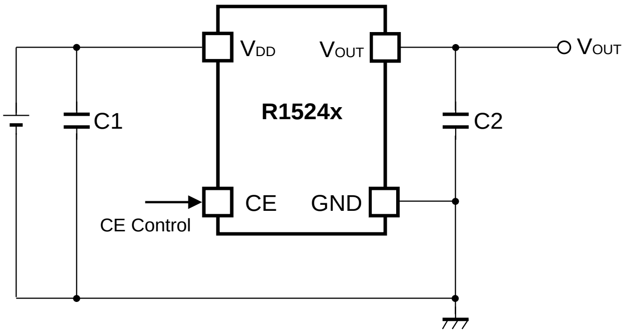
THEORY OF OPERATION

Thermal Shutdown

R1524x has a built-in thermal shutdown circuit, which stops the regulator operation if the junction temperature of this device increases to 160°C (Typ.) or higher. If the temperature drops to 135°C (Typ.) or lower, the regulator restarts the operation. Unless eliminating the overheating problem, the regulator turns on and off repeatedly and as a result, a pulse shaped output voltage is generated.

APPLICATION INFORMATION

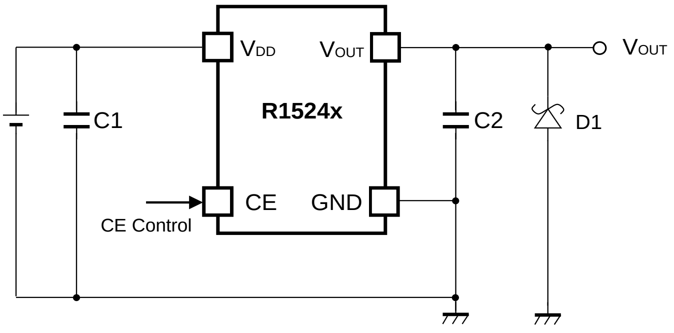
TYPICAL APPLICATIONS



C1 = Ceramic 0.1 µF
C2 = Ceramic 0.1 µF

R1524x Typical Applications

TYPICAL APPLICATION FOR IC CHIP BREAKDOWN PREVENTION



C1 = Ceramic 0.1 µF
C2 = Ceramic 0.1 µF

R1524x Typical Application for IC Chip Breakdown Prevention

When a sudden surge of electrical current travels along the V_{OUT} pin and GND due to a short-circuit, electrical resonance of a circuit involving an output capacitor (C2) and a short circuit inductor generates a negative voltage and may damage the device or the load devices. Connecting a schottky diode (D1) between the V_{OUT} pin and GND has the effect of preventing damage to them.

TECHNICAL NOTES

Phase Compensation

In the R1524x, phase compensation is provided to secure stable operation even when the load current is varied. For this purpose, make sure to use 0.1 μF or more of a capacitor (C2).
In case of using a tantalum type capacitor and the ESR (Equivalent Series Resistance) value of the capacitor is large, the output might be unstable. Evaluate the circuit including consideration of frequency characteristics.
Connect 0.1 μF or more of a capacitor (C1) between V_{DD} and GND, and as close as possible to the pins.

PCB Layout

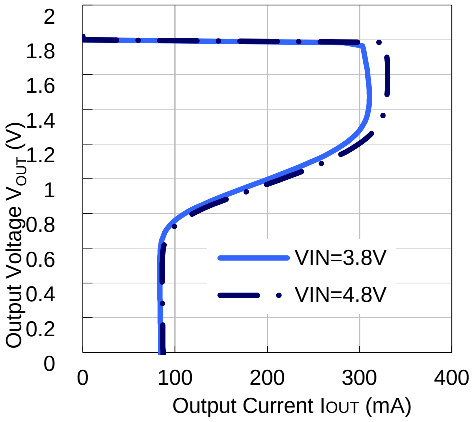
For SOT-23-5 package type, wire the following GND pins together: No. 1 and No. 2
For SOT-89-5 package type, wire the following GND pins together: No. 2 and No. 4.
For HSOP-6J package type, wire the following GND pins together: No. 2, No. 4, and No. 5.

TYPICAL CHARACTERISTICS

Note: Typical Characteristics are intended to be used as reference data; they are not guaranteed.

1) Output Voltage vs. Output Current (Ta = 25°C)

R1524x018B



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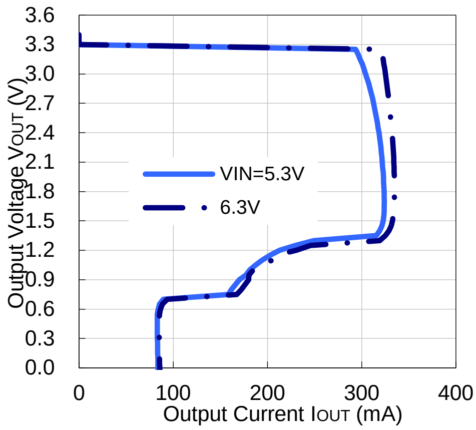
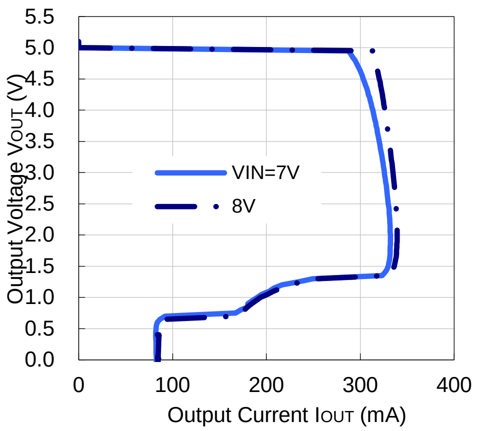


R1524x050B



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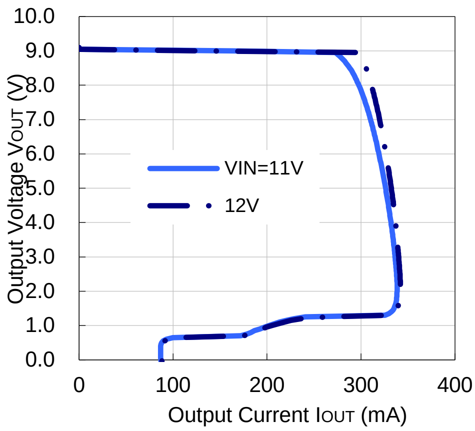
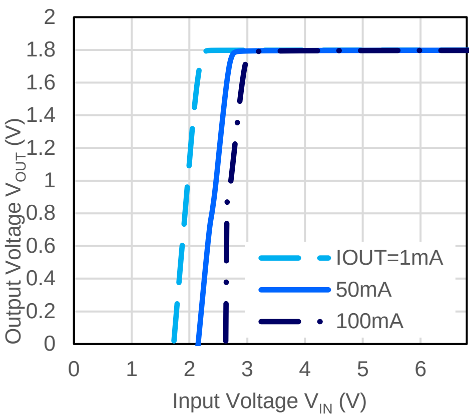


2) Output Voltage vs. Input Voltage (Ta = 25°C)

R1524x018B



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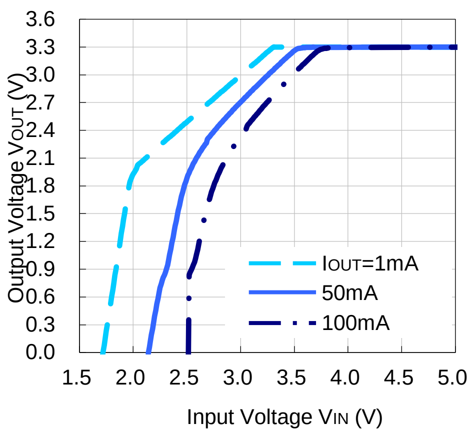

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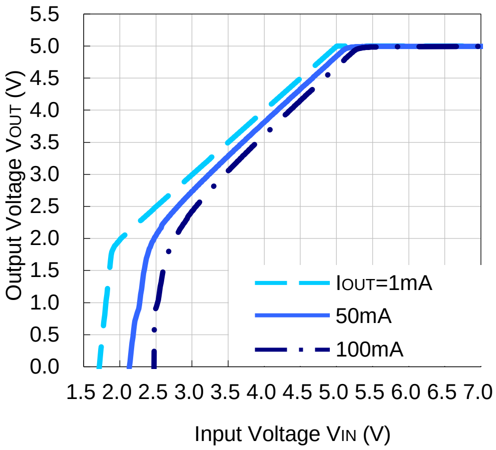

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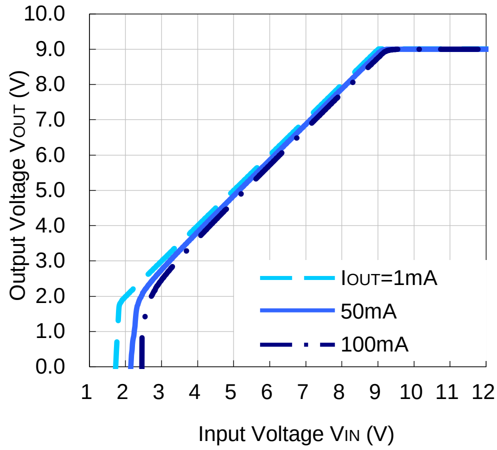
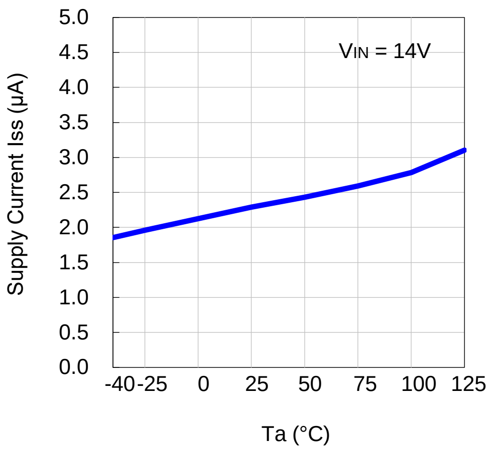


3) Supply Current vs. Temperature

R1524x018B



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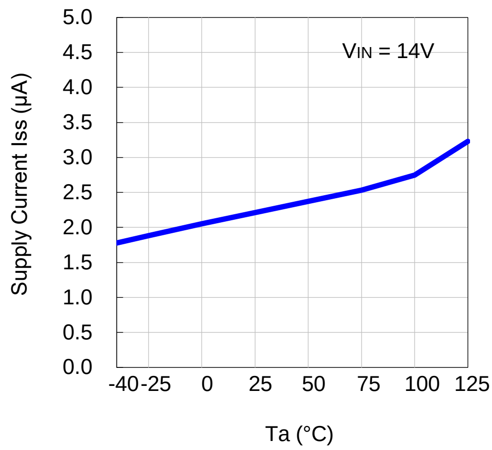

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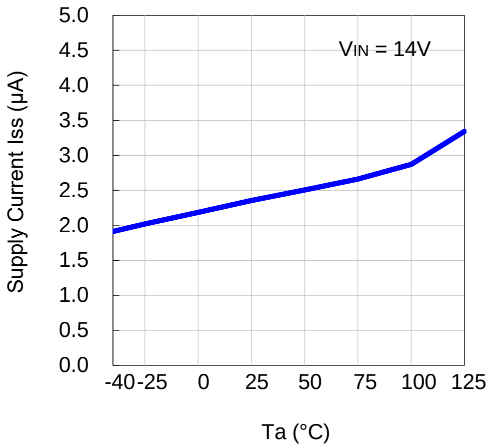

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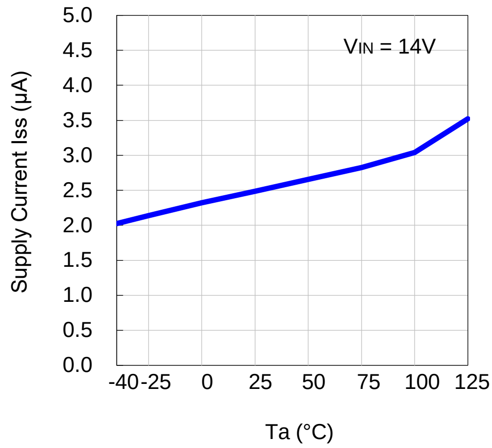
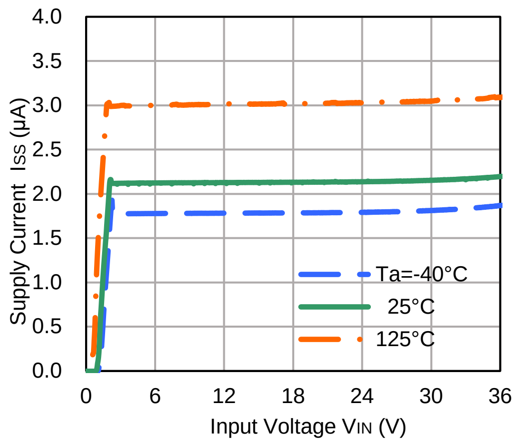


4) Supply Current vs. Input Voltage

R1524x018B



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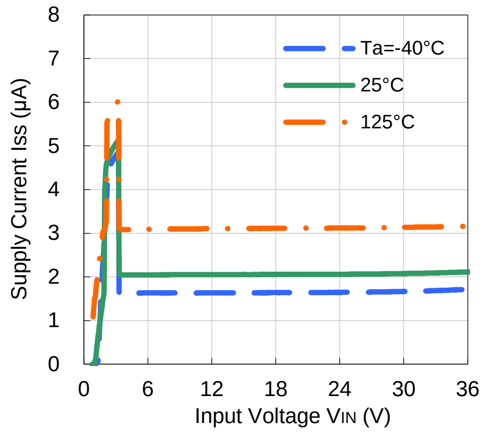

5) Output Voltage vs. Temperature (I_{OUT} = 1mA)

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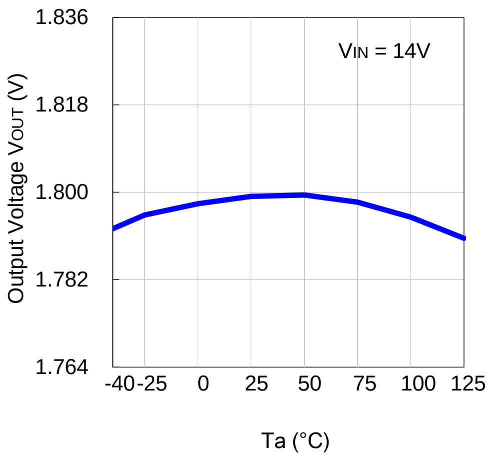

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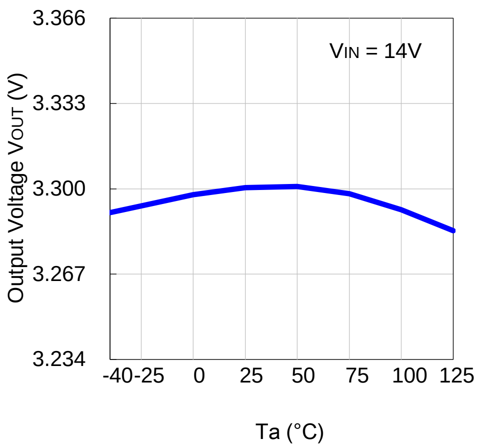

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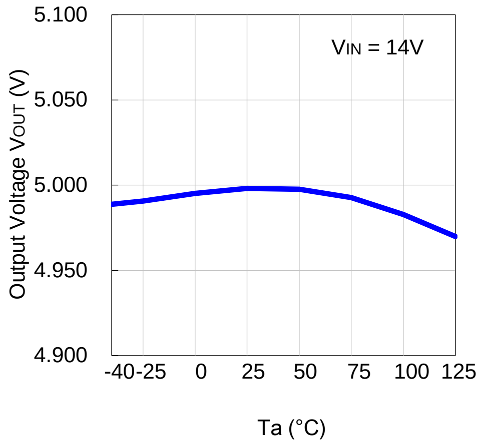

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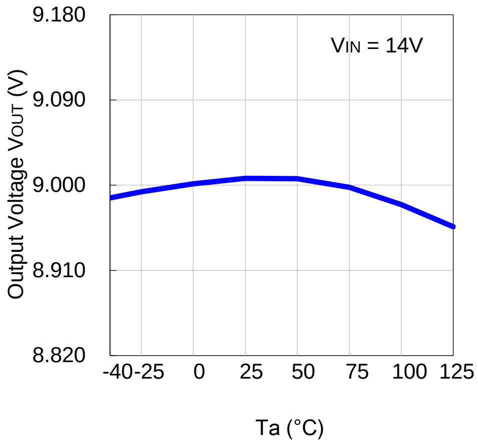
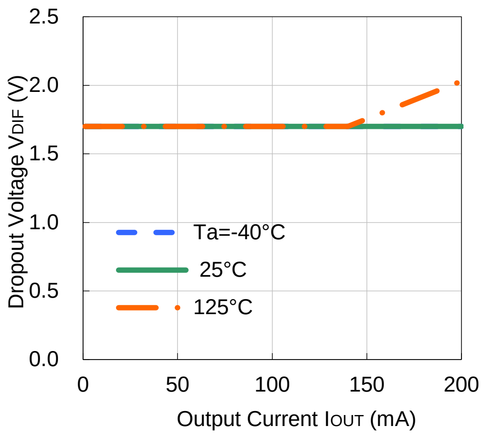


6) Dropout Voltage vs. Output Current

R1524x018B



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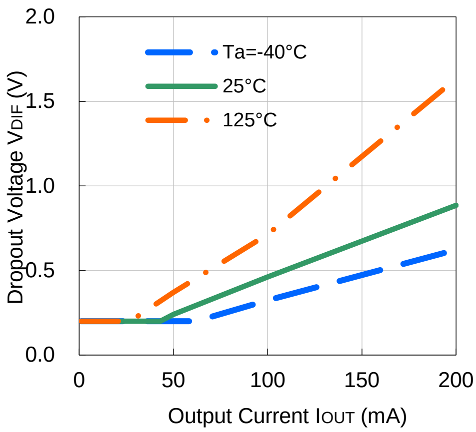

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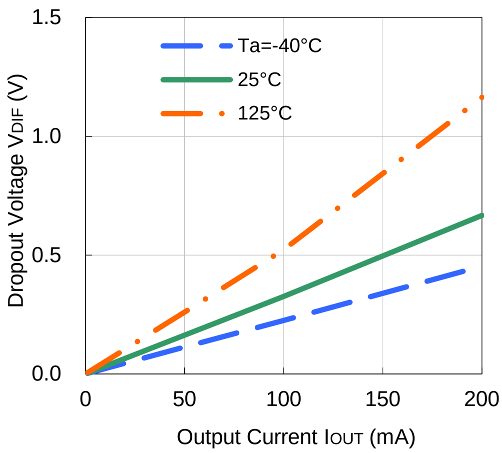

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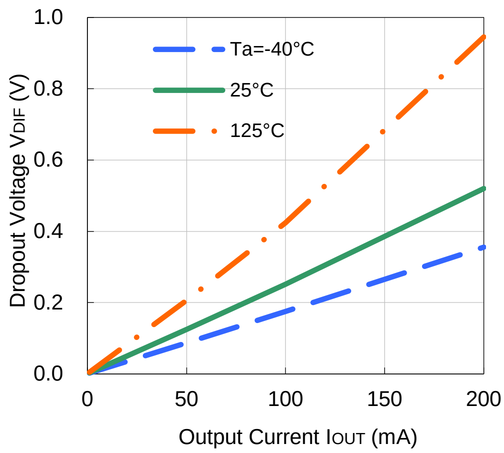
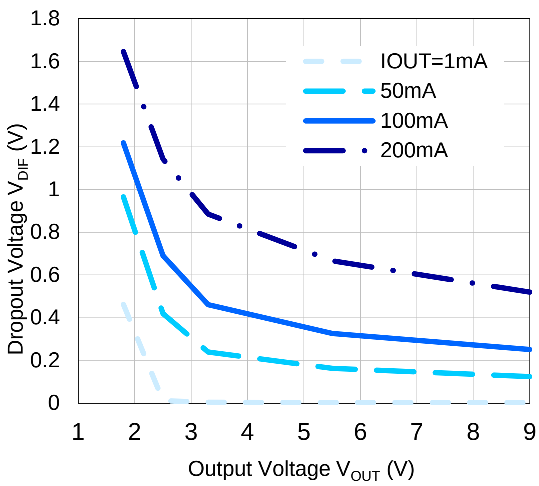


7) Dropout Voltage vs. Output Voltage (Ta = 25°C)



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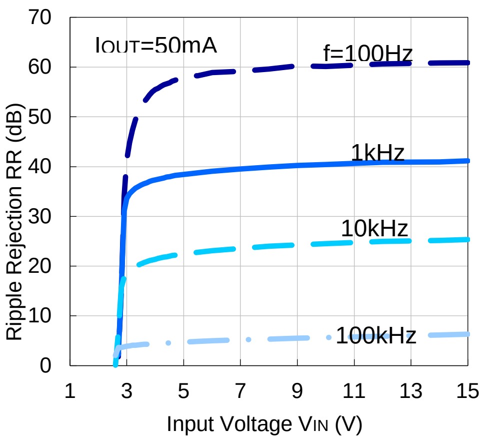
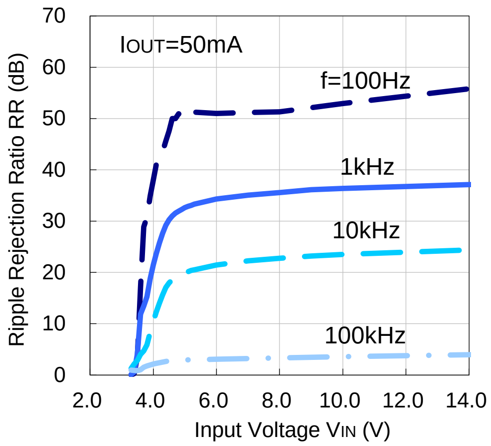
8) Ripple Rejection vs. Input Voltage (Ta = 25°C, Ripple = 0.2 Vpp)

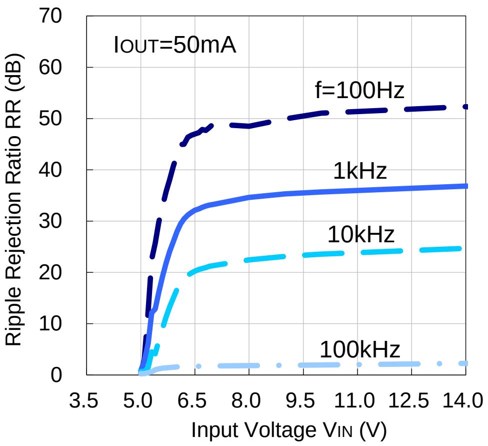
R1524x018B



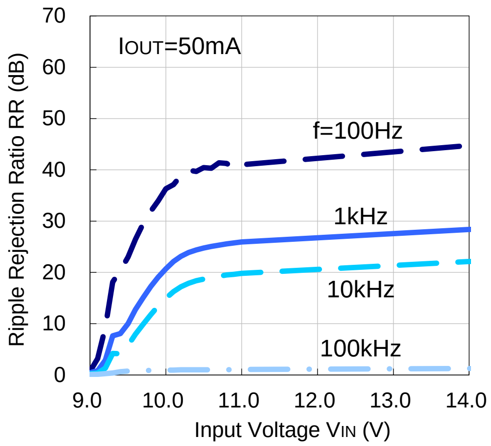
R1524x033B



R1524x050B

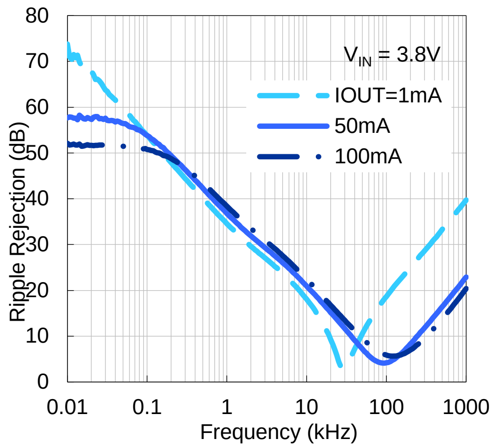


R1524x090B

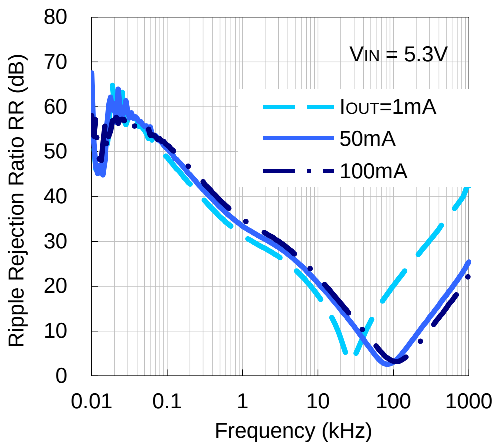


9) Ripple Rejection vs. Frequency (Ta = 25°C, Ripple = 0.2 Vpp)

R1524x018B

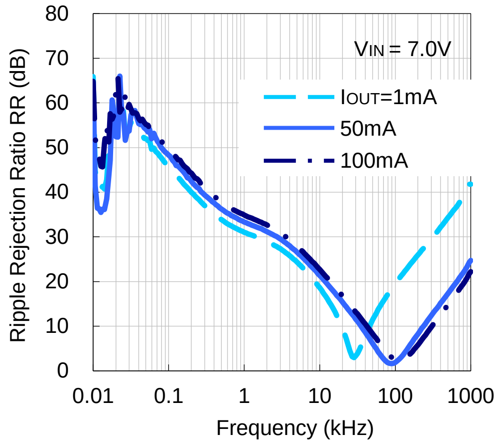


R1524x033B

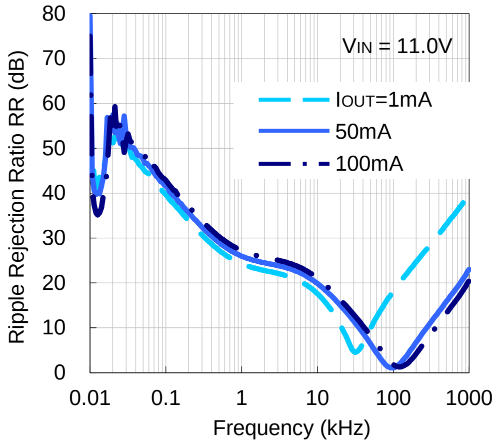


RICOH

R1524x050B

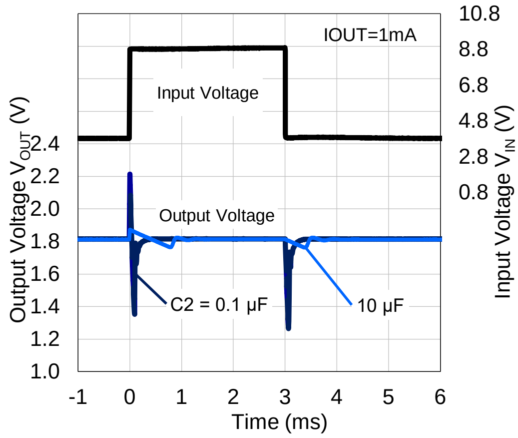


R1524x090B

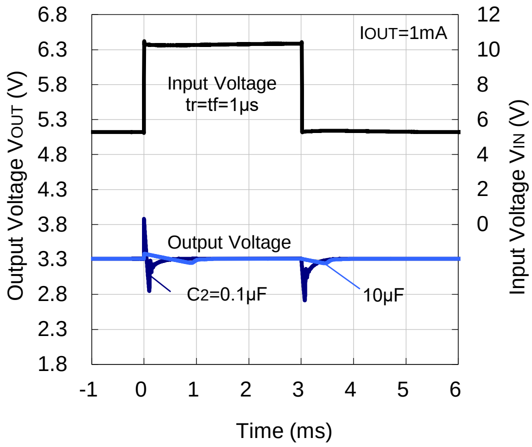


10) Input Transient Response (Ta = 25°C)

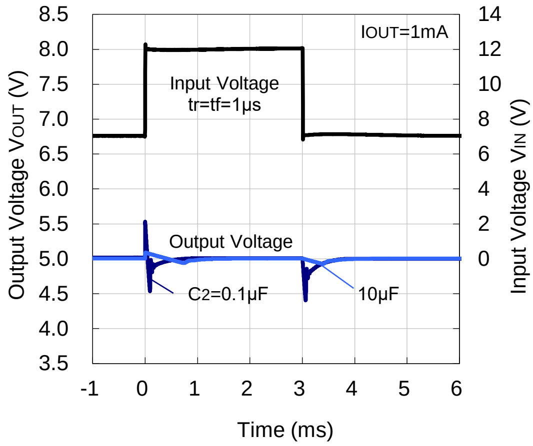
R1524x018B



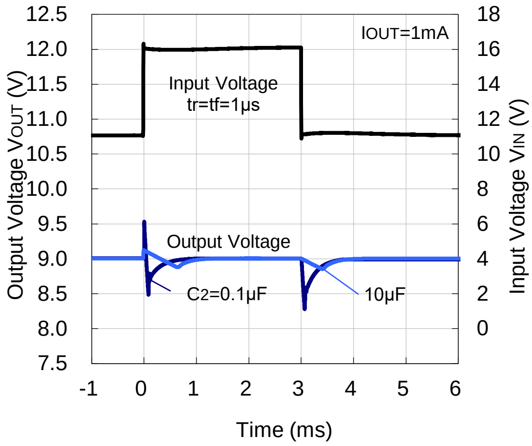
R1524x033B



R1524x050B

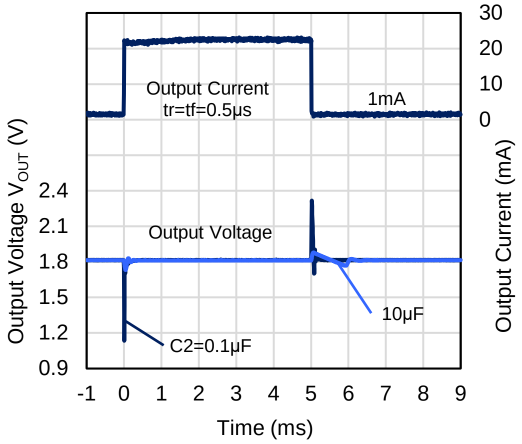


R1524x090B

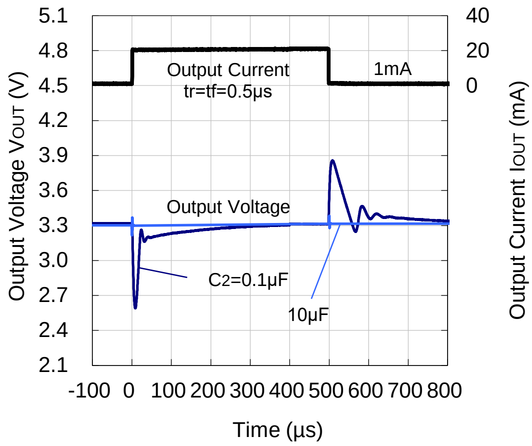


11) Load Transient Response (Ta = 25°C)

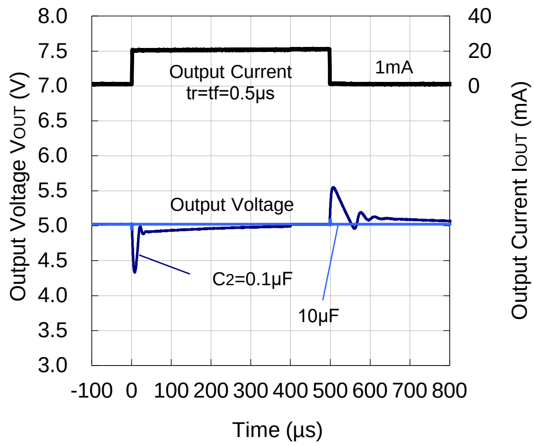
R1524x018B



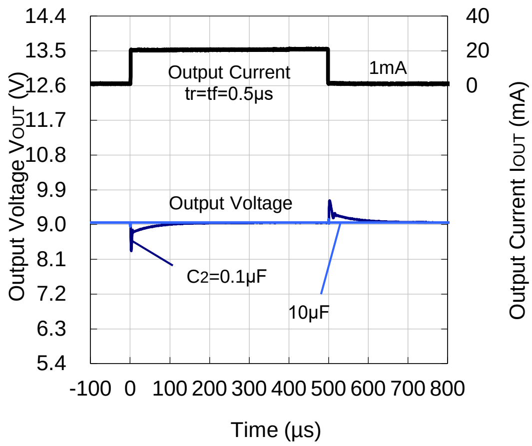
R1524x033B



R1524x050B

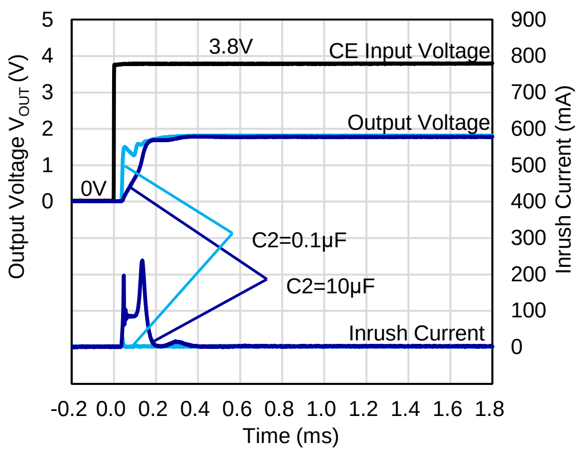


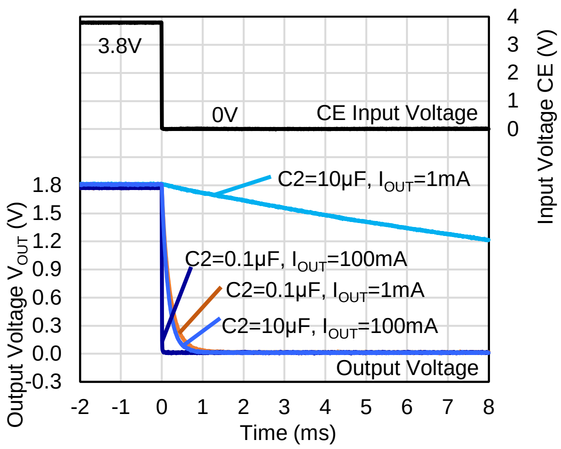
R1524x090B



12) CE Transient Response (Ta = 25°C)

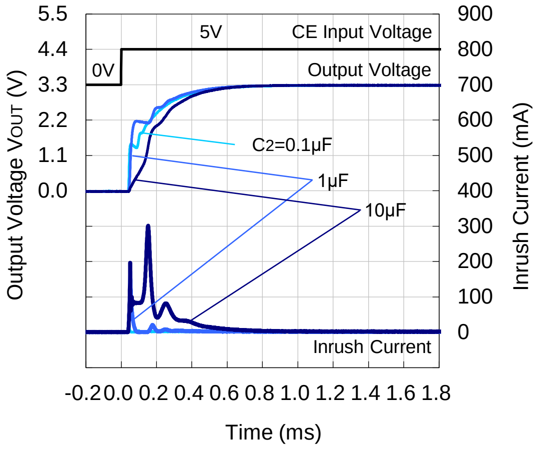
R1524x018B

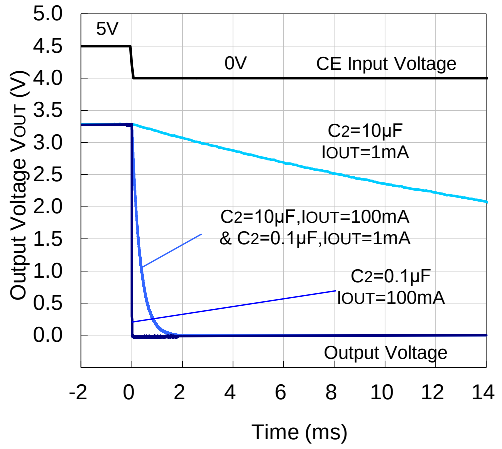




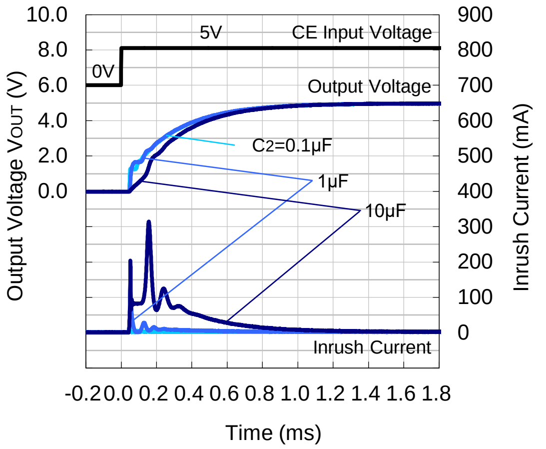
RICOH

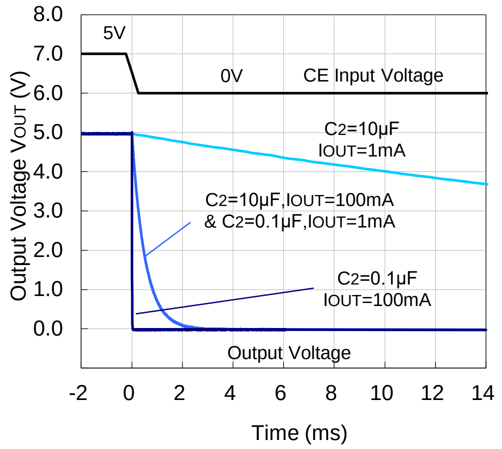
R1524x033B



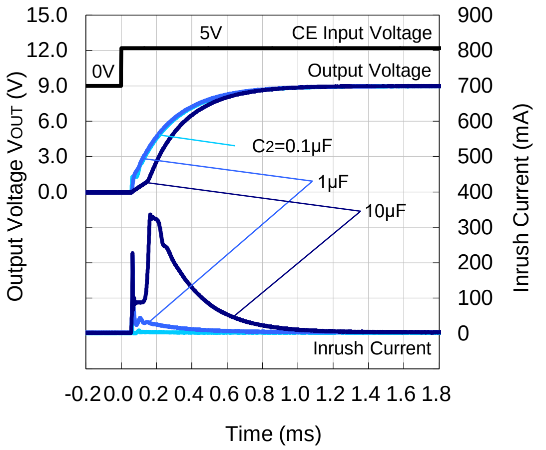


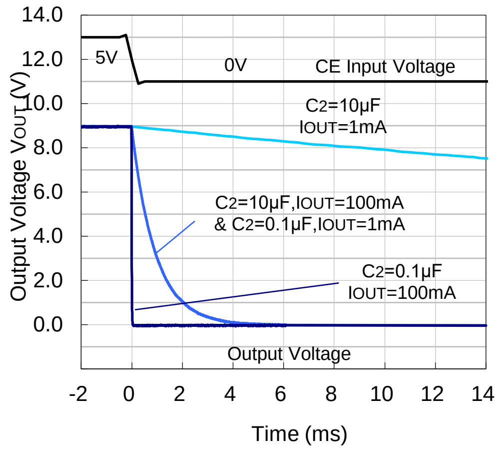
R1524x050B





R1524x090B

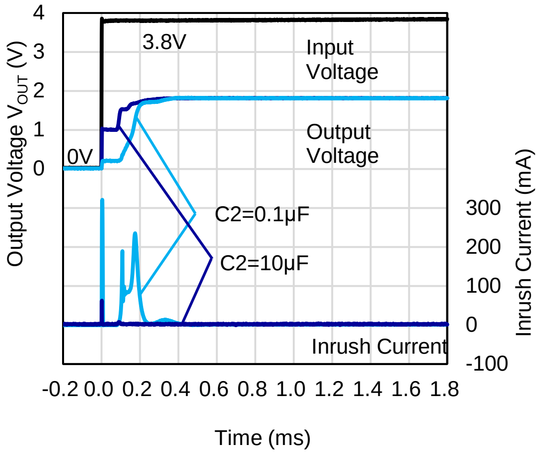




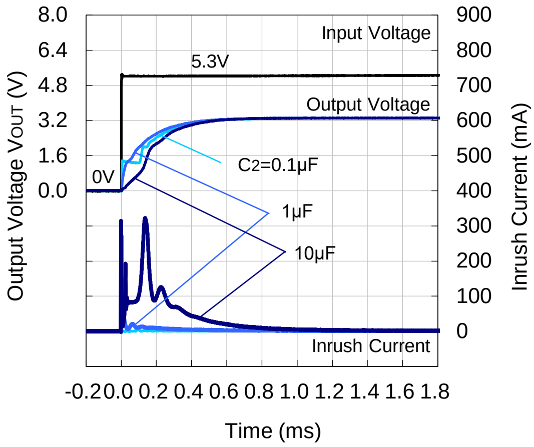
RICOH

13) Power-on Transient Response (Ta = 25°C, V_{CE} = 5 V)

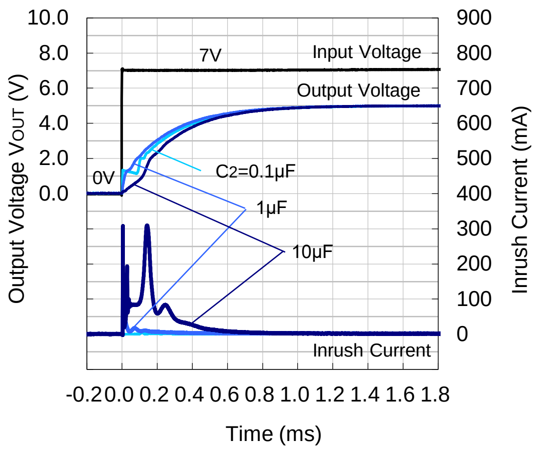
R1524x018B



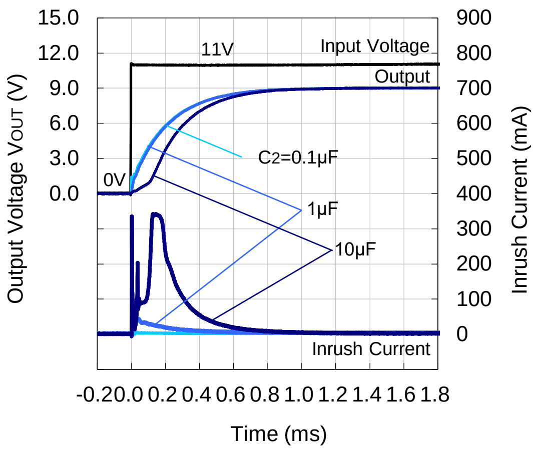
R1524x033B



R1524x050B

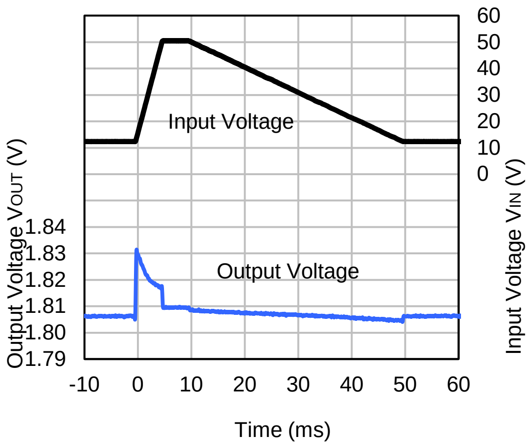


R1524x090B

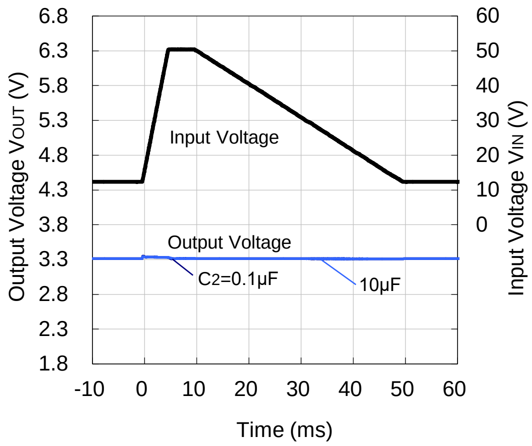


14) Load Dump (Ta = 25°C)

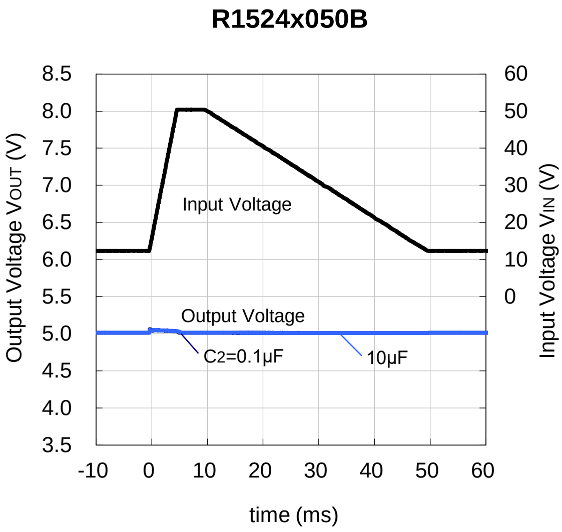
R1524x018B

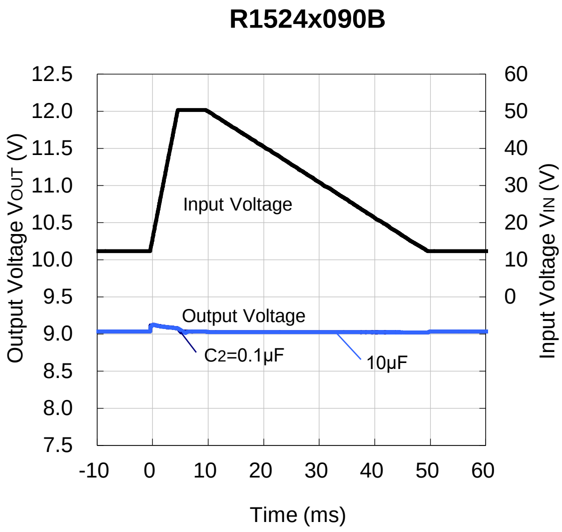


R1524x033B

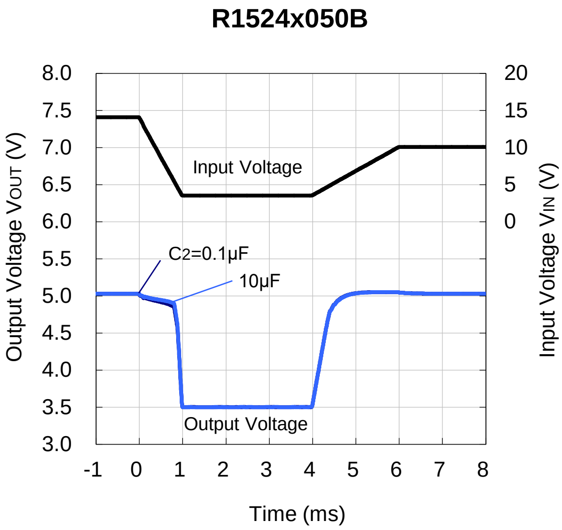


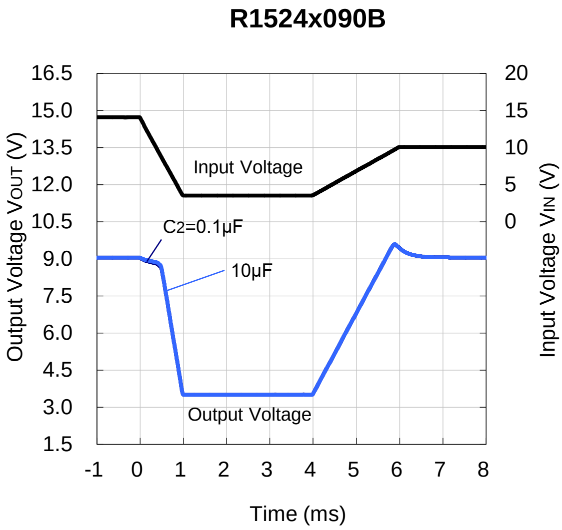
RICOH





15) Cranking (Ta = 25°C)



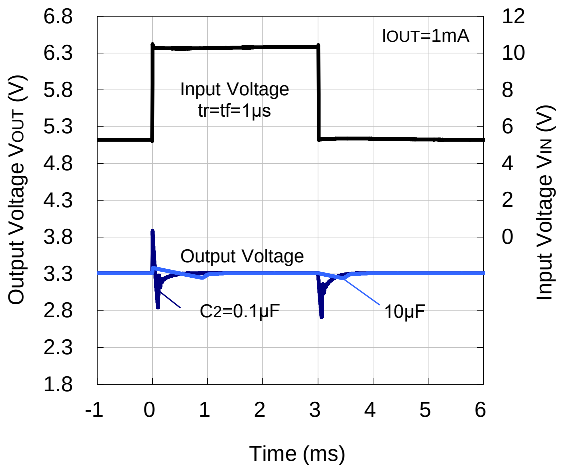


Input Transient/Load Transient vs. Output Capacity (C2)

R1524 performs a stable operation by using 0.1 µF of ceramic capacitor as the output capacitor. However, the variation of output voltage may not meet the demand of the system when input voltage and load current vary. In such cases, the variation of output voltage can be minimized significantly by using 10 µF or higher ceramic capacitor. When using an electrolytic capacitor for the output line, place the electrolytic capacitor outer side of the ceramic capacitor arranged close to the IC.

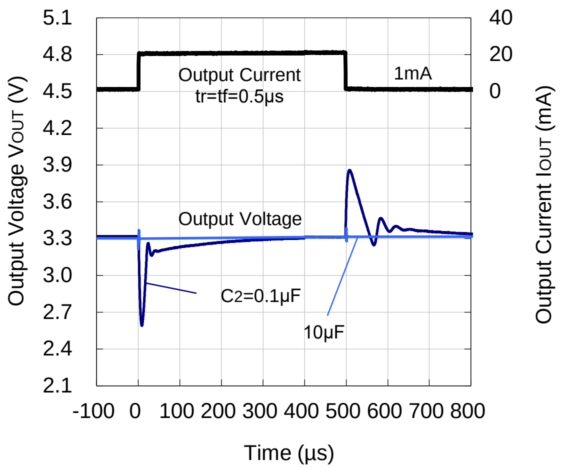
Input Transient Response

R1524x033B



Load Transient Response

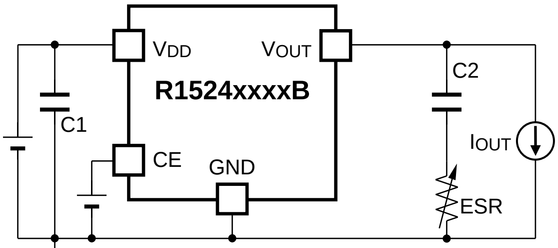
R1524x033B



RICOH

ESR vs. Output Current

It is recommended that a ceramic type capacitor be used for this device. However, other types of capacitors having lower ESR can also be used. The relation between the output current (I_{OUT}) and the ESR of output capacitor is shown below.

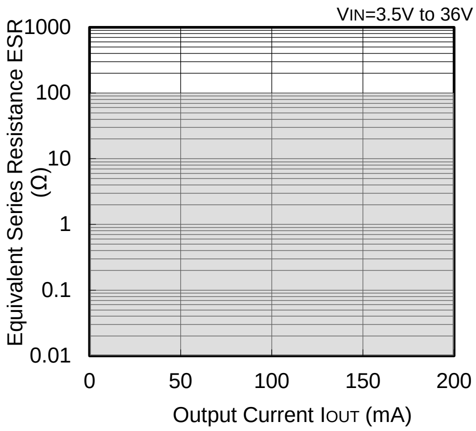


C1 = Ceramic 0.1 μF, C2 = Ceramic 0.1 μF

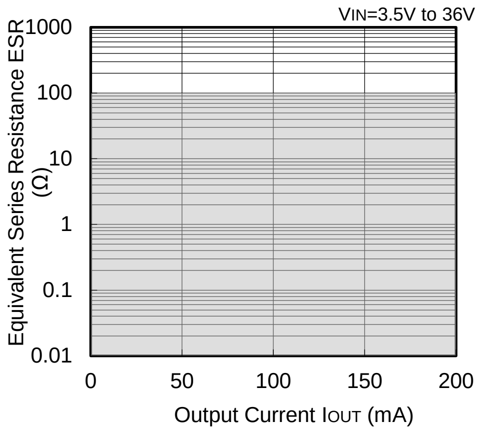
Measurement Conditions

Frequency Band: 10 Hz to 2 MHz
Measurement Temperature: −40°C to 125°C
Hatched area: Noise level is 40 μV (average) or below
Ceramic Capacitors: C1 = 0.1 μF, C2 = 0.1 μF

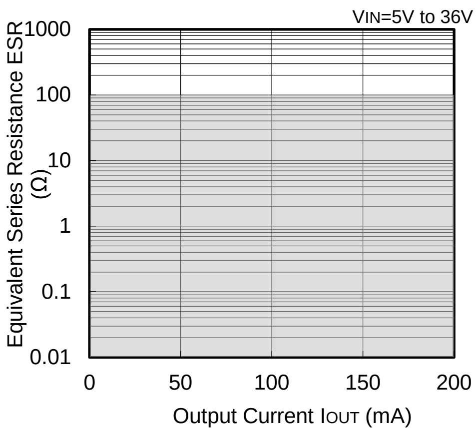
R1524x018B



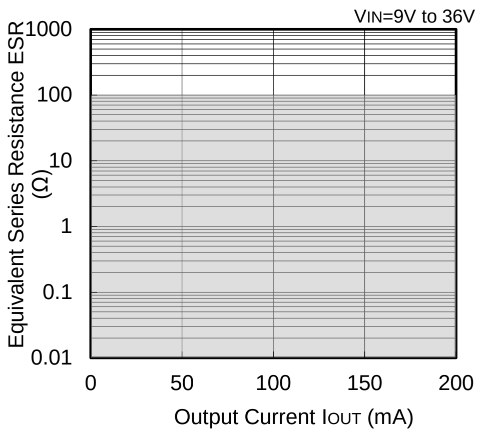
R1524x033B



R1524x050B



R1524x090B



Ver. A

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

Measurement Conditions

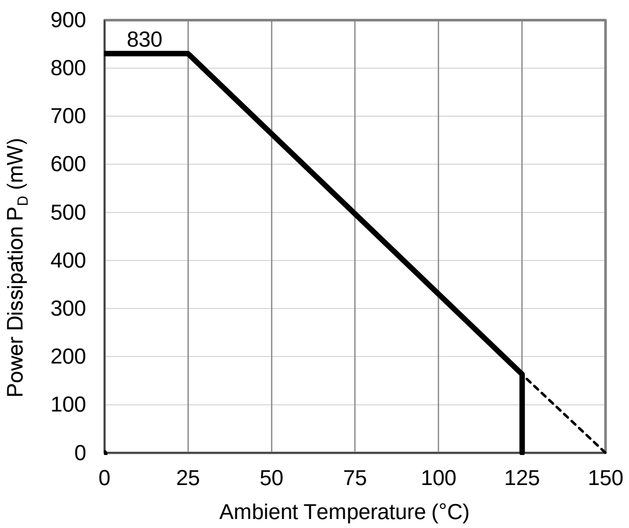
Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	ϕ 0.3 mm × 7 pcs

Measurement Result (Ta = 25°C, Tjmax = 150°C)

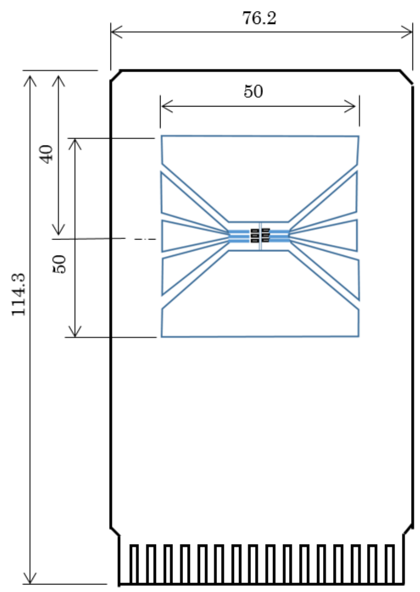
Item	Measurement Result
Power Dissipation	830 mW
Thermal Resistance (θja)	θja = 150°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 51°C/W

θja: Junction-to-Ambient Thermal Resistance

ψjt: Junction-to-Top Thermal Characterization Parameter



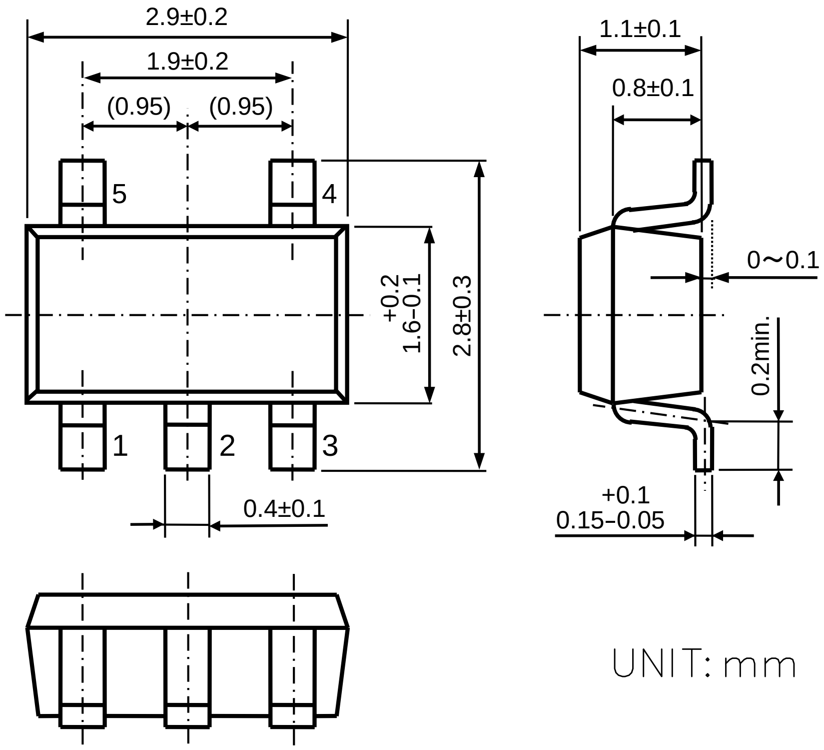
Power Dissipation vs. Ambient Temperature



Measurement Board Pattern

RICOH

Ver. A



SOT-23-5 Package Dimensions

Ver. A

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

Measurement Conditions

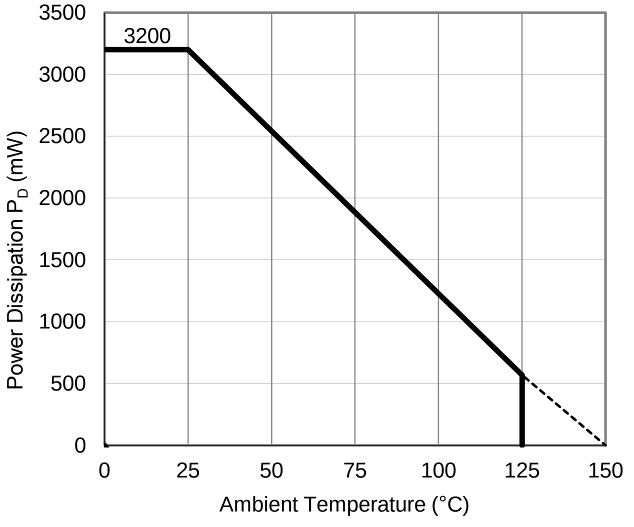
Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	ϕ 0.3 mm × 13 pcs

Measurement Result (Ta = 25°C, Tjmax = 150°C)

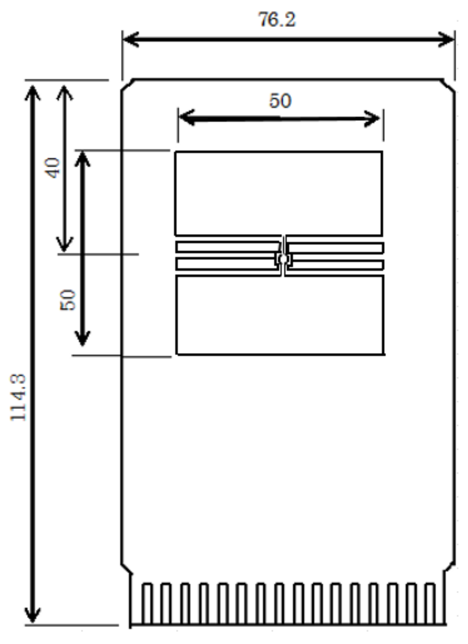
Item	Measurement Result
Power Dissipation	3200 mW
Thermal Resistance (θja)	θja = 38°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 13°C/W

θja: Junction-to-Ambient Thermal Resistance

ψjt: Junction-to-Top Thermal Characterization Parameter

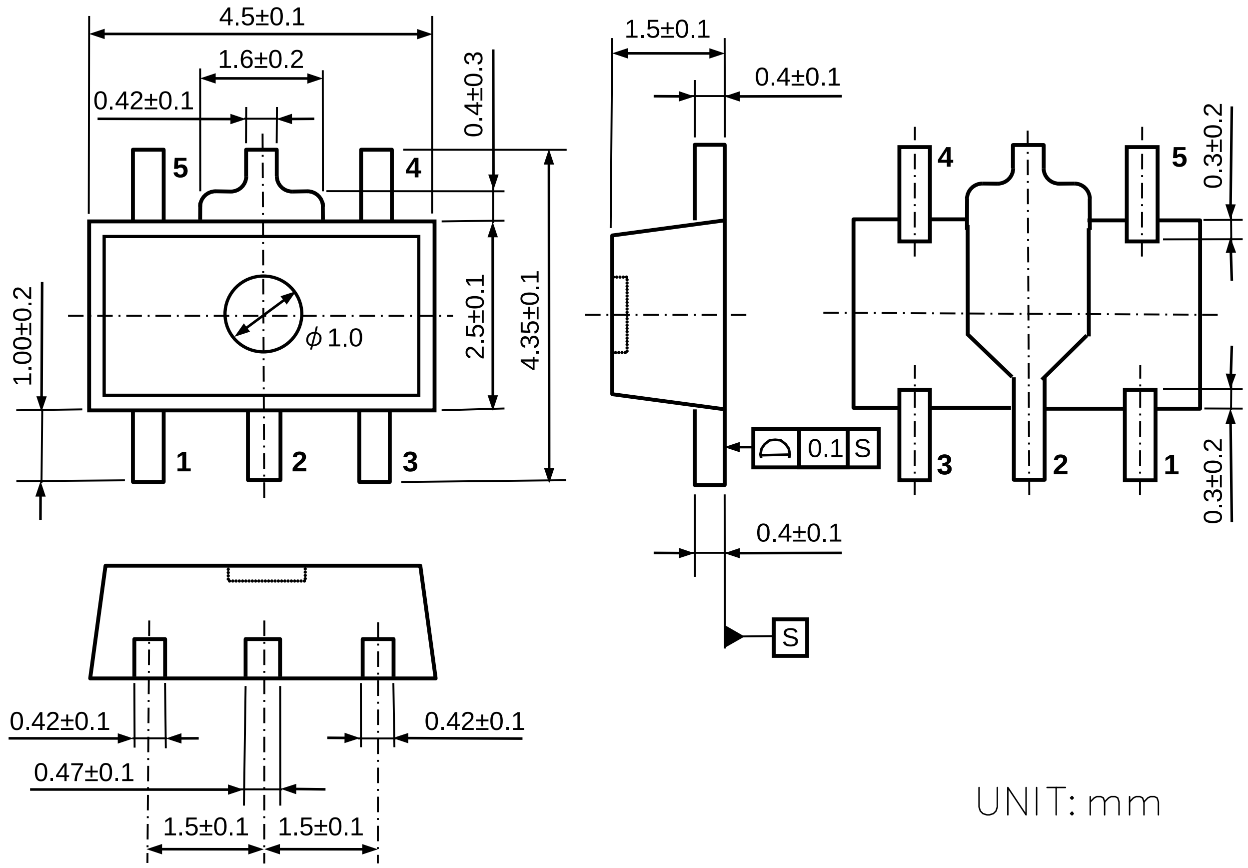


Power Dissipation vs. Ambient Temperature



Measurement Board Pattern

RICOH



SOT-89-5 Package Dimensions

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

Measurement Conditions

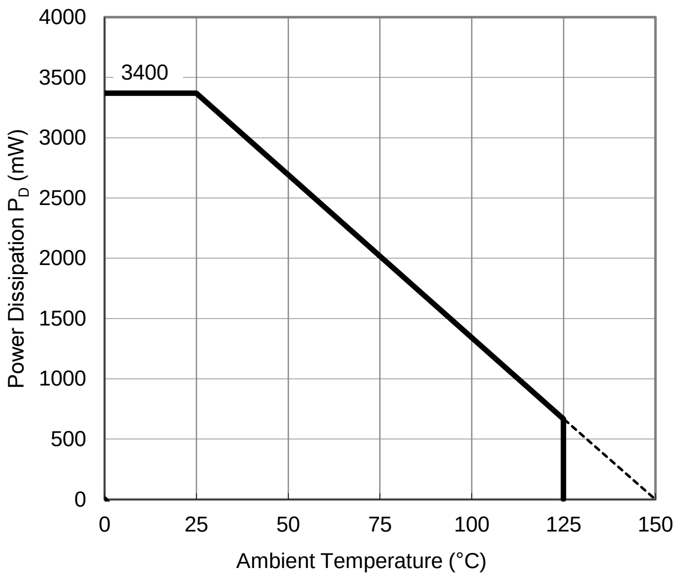
Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	ϕ 0.3 mm × 28 pcs

Measurement Result (Ta = 25°C, Tjmax = 150°C)

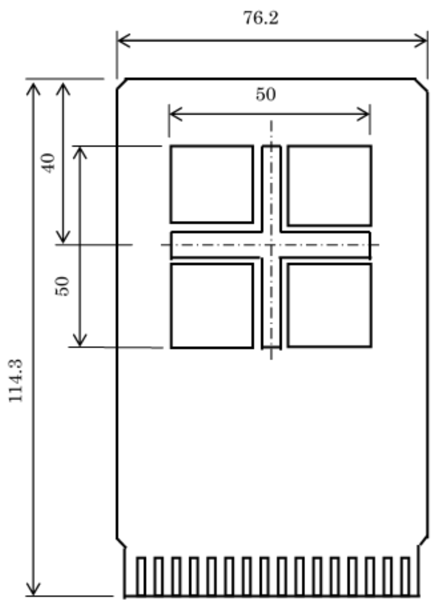
Item	Measurement Result
Power Dissipation	3400 mW
Thermal Resistance (θja)	θja = 37°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 7°C/W

θja: Junction-to-Ambient Thermal Resistance

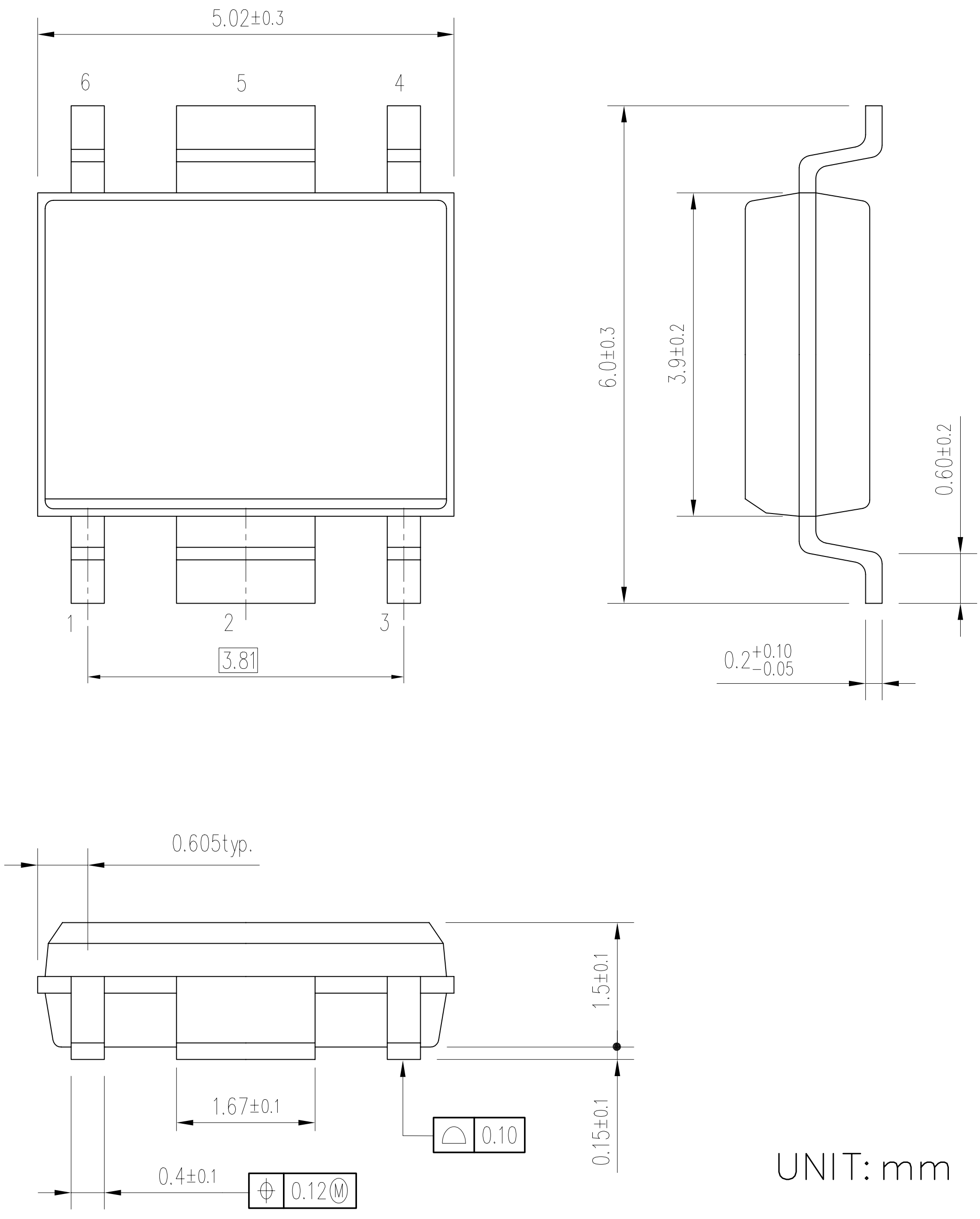
ψjt: Junction-to-Top Thermal Characterization Parameter



Power Dissipation vs. Ambient Temperature



Measurement Board Pattern



HSOP-6J Package Dimensions

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

Measurement Conditions

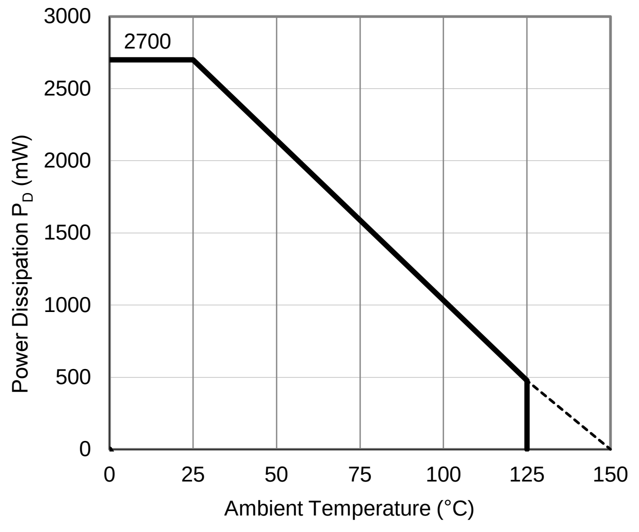
Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	ϕ 0.2 mm × 34 pcs

Measurement Result (Ta = 25°C, Tjmax = 150°C)

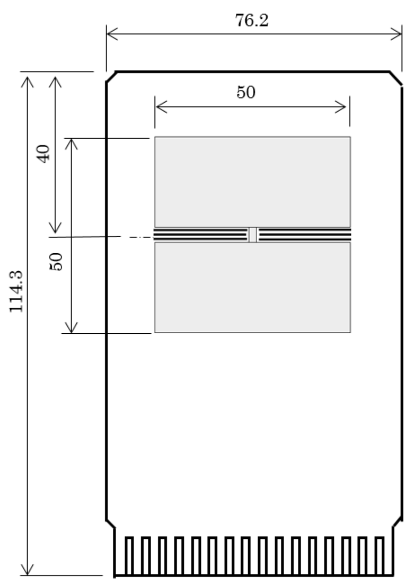
Item	Measurement Result
Power Dissipation	2700 mW
Thermal Resistance (θja)	θja = 45°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 18°C/W

θja: Junction-to-Ambient Thermal Resistance

ψjt: Junction-to-Top Thermal Characterization Parameter

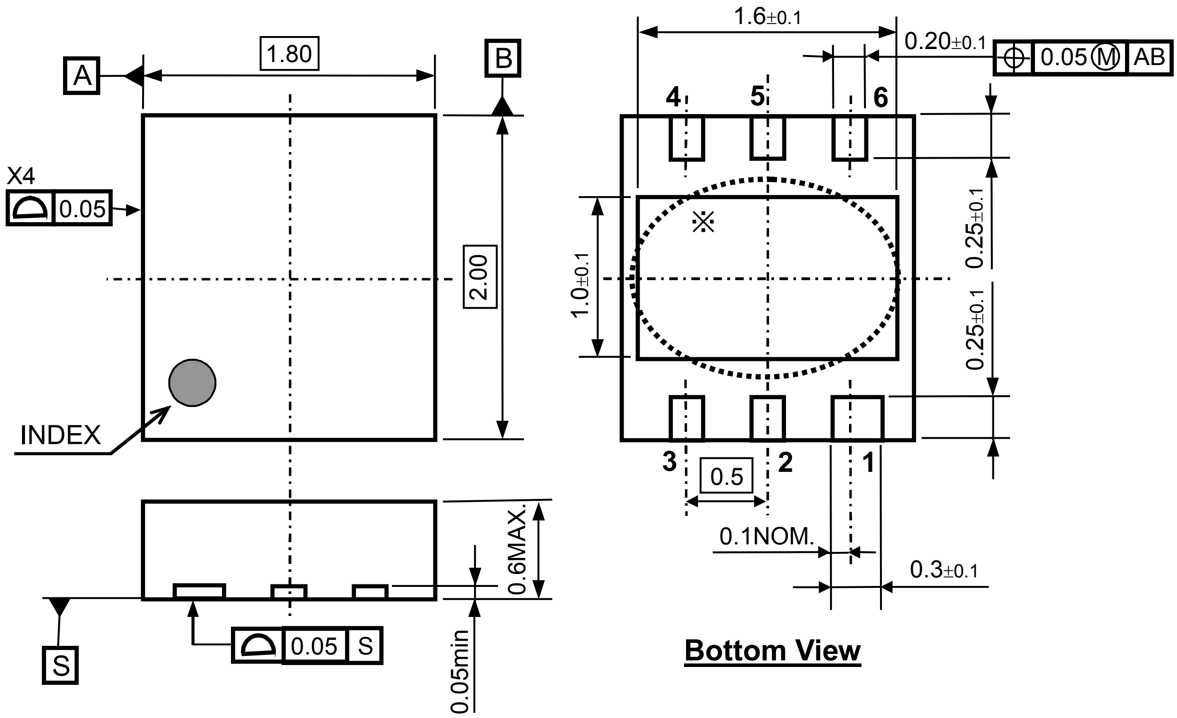


Power Dissipation vs. Ambient Temperature



Measurement Board Pattern

Ver. A



DFN(PLP)1820-6 Package Dimensions (Unit: mm)

∗ The tab on the bottom of the package is substrate level (GND). It is recommended that the tab be connected to the ground plane on the board, or otherwise be left floating.

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

Measurement Conditions

Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	ϕ 0.3 mm × 21 pcs

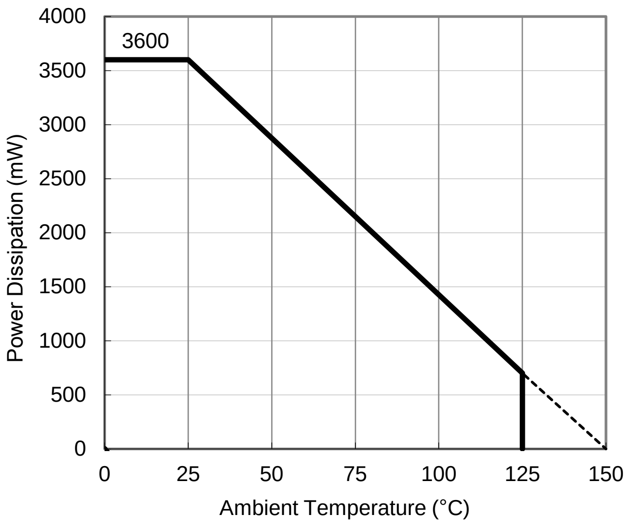
Measurement Result

(Ta = 25°C, Tjmax = 150°C)

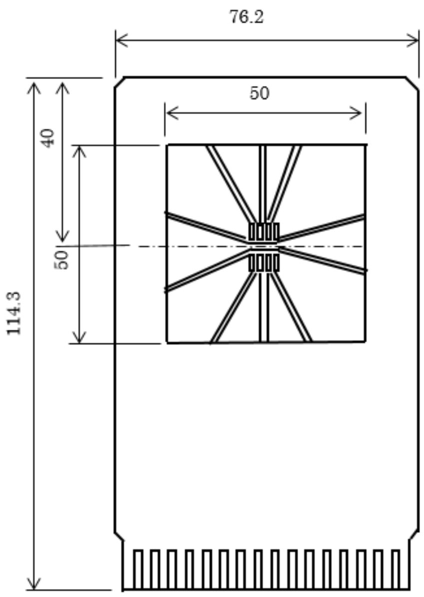
Item	Measurement Result
Power Dissipation	3600 mW
Thermal Resistance (θja)	θja = 34.5°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 10°C/W

θja: Junction-to-Ambient Thermal Resistance

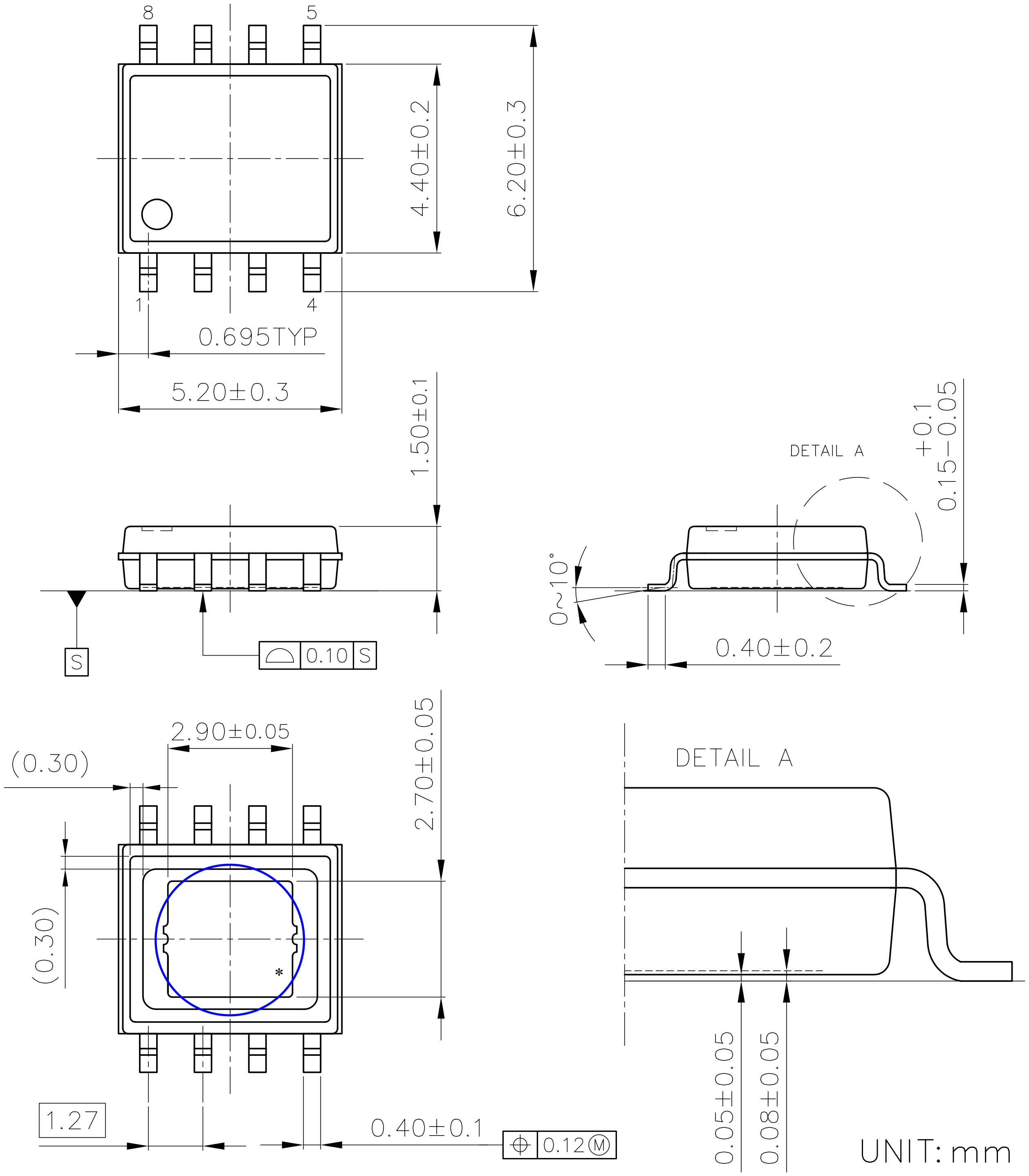
ψjt: Junction-to-Top Thermal Characterization Parameter



Power Dissipation vs. Ambient Temperature



Measurement Board Pattern



HSOP-8E Package Dimensions

* The tab on the bottom of the package shown by blue circle is substrate potential (GND). It is recommended that this tab be connected to the ground plane on the board but it is possible to leave the tab floating.

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